

# TouchChip® TCET Module

Silicon Fingerprint Module



### **APPLICATIONS**

ID Verification for:

- Civil ID/Voting/Entitlement
- Physical Access
- · Finance, Healthcare and Point of Sale
- Mobile ID terminals

### PRODUCT DESCRIPTION

The TouchChip TCET module is compact, cost effective and easy to integrate. The on-board processor is used for capture and match, delivering fast and accurate results. It can store up to approximately 100 user templates and supports USB, SPI or UART interfaces. Power consumption is less than 100mA during capture and match.

For easy integration, the TCET module is fully assembled and tested. Just connect and interface with simple commands. The Enhanced Image Mode (EIM) optimizes image quality over a broad range of skin types and capture conditions. The TCET module eliminates latent images during capture and offers ingress protection from dust and moisture penetration to IP65\*. The module supports WSQ and JPEG2000 compression with the appropriate Software Development Kit.

Crossmatch® offers two TouchChip TCET module options:

- TCETC1 (uses the TCS1CT sensor to provide FIPS 201 certification)
- TCETD1 (uses the TCS1ST for enhanced durability)

The TouchChip TCET module includes broad software support from leading algorithm providers, ISV's and system integrators. Whether you are an OEM or system integrator, Crossmatch's biometric identity verification solutions provide a natural extension to your applications.

## ABOUT CROSSMATCH

Crossmatch helps organizations solve their identity management challenges through biometrics. Our enrollment and authentication solutions are trusted to create, validate and manage identities for a wide range of government, law enforcement, financial institution, retail and commercial applications. Our solutions are designed using proven biometric technologies, flexible enrollment and strong multi-factor authentication software, and deep industry expertise. We offer an experienced professional services capability to assess, design, implement and optimize our identity management solutions for a customer's individual challenges. Our products and solutions are utilized by over 200 million people in more than 80 countries.

Learn more at www.crossmatch.com

<sup>\*</sup> Requires customer to add external gasket.

# TouchChip® TCET Module

Silicon Fingerprint Module



### **SPECIFICATIONS**

Interface	<ul><li>12-pin flex: USB, SPI, UART @ 3.3v</li><li>5-soldier pads for USB only @ 5v</li></ul>
Power (typical)	<ul><li>3.0v to 3.6v</li><li>100mA (capture, match)</li><li>Standby (USB): 1350 uA</li><li>Standby (UART/SPI): 1150 uA</li></ul>
Fingerprint Image	<ul><li>12.8 x 18.0 mm (256 x 360 pixels)</li><li>508 dpi, 8-bit grayscale</li></ul>
Sensor Coating	<ul><li>FIPS 201 (gold coating)</li><li>SteelCoat (black coating)</li></ul>
Package Size	• 23 mm x 35 mm x 4.1 mm
ESD	• IEC 61000 - 4.2 level 4, +/- 15KV air, +/- 8KV contact
Ingress Protection	• IP65 (water/dust protection)*
Environmental	<ul> <li>Operating temp: -30 to +70 C</li> <li>Storage temp: -30 to +125 C</li> <li>Humidity: 5% - 93% non-condensing</li> </ul>
TCS1 FIPS 201 3.3v USB/SPI/UART Silver Bezel	• TCETC1FF022
TCS1 FIPS 201 5v USB only Silver Bezel	• TCETC1FG022
TCS1 SteelCoat 3.3v USB/SPI/UART Silver Bezel	• TCETD1FF022
TCS1 SteelCoat 5v USB only Silver Bezel	• TCETD1FG022
TCS1 FIPS 201 3.3v USB/SPI/UART Black Bezel	• TCETC1PF022
TCS1 FIPS 201 5v USB only Black Bezel	• TCETC1PG022

Data subject to change without notice

# **FEATURES**

- FIPS 201 PIV certified
- SteelCoat
- Low power consumption
- · Compact size
- High durability silicon surface
- IP65-rated top surface sealed against dust and liquid\*
- High quality fingerprint image
- OS: Windows<sup>®</sup> 7, 8 and 10, Win CE, Linux<sup>®</sup>, Android and embedded systems (with and without OS)

Corporate Headquarters:

Crossmatch

3950 RCA Boulevard, Suite 5001 Palm Beach Gardens, FL 33410 USA

www.crossmatch.com

<sup>\*</sup> Requires customer to add external gasket.